What is claimed is:

1.A heat-dissipating stand device for use with a personal computer of the notebook, laptop, personal planner, or pen-type input types, said stand device comprising:

a. a heat-conductive planar member dimensioned to be as large as or smaller than the footprint of the bottom side of said personal computer;

b. at least one retaining means to maintain a desired positioning of the planar member with respect to the bottom side of said personal computer, said retaining means selected from the group consisting of a textured non-slip finish, at least one retaining ridge, hook and loop type attachments adhered at selected points on said planar member and said bottom side; at least one vinyl pad positioned on the top surface of said planar member; stretchable straps from points on said planar member, spanning one or more sections of said personal computer; and an elevated lip at or near the front top edge of said planar member; and

c. at least one retractable leg attached toward the rear edge of said planar member, disposed for elevating said rear edge when in an extended position;

Wherein upward-directed ridges on said planar member top surface and/or the thickness of said retaining means provide a gap for passage of cooling air between said bottom side and said planar member, and whereby placement of said stand device increases heat dissipation from said personal computer during its operation.

2. The heat-dissipating stand device of claim 1, additionally comprising vinyl covers on the bottom points of contact of the stand device with a surface below said device, particularly on the front bottom edge of the planar member, and on the lowest-

projecting aspects of the at least one retractable leg.

3. The heat-dissipating stand device of claim 1, additionally comprising at least one void in said heat-conductive planar member.

4. The heat-dissipating stand device of claim 3, wherein there are four voids, formed in the shape of long slots extending in a linear front-to-back direction on the heat-conductive planar member, and spaced apart by at least the width of one of said slots.

5. The heat-dissipating stand device of claim 1, wherein said planar member is substantially comprised of a material with a specific thermal conductivity between 50 and 300 W/m•K.

6. The heat-dissipating stand device of claim 1, wherein said planar member is substantially comprised of a material with a specific thermal conductivity between 50 and 100 W/m•K.

7. The heat dissipating stand device of claim 1, wherein said planar member is substantially comprised of a material with a specific thermal conductivity between

60 and 90 W/m•K.

8. The heat dissipating stand device of claim 1, wherein said planar member is substantially comprised of a material with a specific thermal conductivity between 60 and 75 W/m•K.

9. The heat-dissipating stand device of claim 1, wherein said planar member is substantially comprised of a material with a specific thermal conductivity between

200 and 300 W/m•K.

10. The heat-dissipating stand device of claim 1, wherein said planar member is substantially comprised of a material with a specific thermal conductivity between 220 and 280 W/m•K.

11. The heat-dissipating stand device of claim 1, wherein said planar member is substantially comprised of a material with a specific thermal conductivity between 240 and 270 W/m•K.

12. The heat-dissipating stand device of claim 1, wherein said at least one retractable leg is hingedly attached to the planar member.

13. The heat-dissipating stand device of claim 6, wherein said at least one retractable leg is retractable by hinging toward the planar member plane to a closed position.

14. The heat-dissipating stand device of claim 1, additionally comprising two or more outward-projecting extensions co-planar with the planar member, positioned to support the bottom of said laptop computer, where said laptop computer extends beyond the edges of said planar member.

15. The heat-dissipating stand device of claim 14, wherein said two or more outward-projecting extensions co-planar with the planar member are rectangular in shape and insert into slots on said planar member.

16. The heat-dissipating stand device of claim 1, wherein the heat-conductive planar member is substantially comprised of the aluminum alloy designated as 6061-T6.

17. The heat-dissipating stand device of claim 1, wherein the heat-conductive planar member is substantially comprised of the mesophase pitch-derived graphitic foam designated as PocoFoam.

18. The heat dissipating stand device of claim 1, wherein the heat-conductive planar member is dimensioned to support the majority of said personal computers with nominal sizes of 12 to 16 inches, and wherein the larger of said personal computers overhang said heat-conductive planar member.